

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.-5. (Cancelled)

6. (Currently Amended and Withdrawn) A method of manufacturing the conductive pattern as claimed in ~~claim 1-claim 54~~, comprising the steps of:

forming ~~a-the~~ plurality of first conductive strip halves having a given width on an electrically insulating surface of a substrate such that the first conductive strip halves are separated from each other to form depressions having a given width;

forming ~~a-the~~ first insulating film on the surface of the substrate and surfaces of the depressions formed between successive first conductive strip halves;

forming a resist selectively on areas at which said first conductive strip halves are formed;

forming ~~a-the~~ second insulating film on a portion of the surface of the substrate which are not covered with the resist;

forming, after removing said resist, a conductive film such that the depressions formed between successive first conductive strip halves are filled with the conductive film;

polishing the conductive film, the first and second insulating films formed on the first conductive strip halves such that the first conductive strip halves are exposed to form ~~a-the~~ plurality of second conductive strip halves embedded in said depressions formed between successive first conductive strip halves; and

forming a third insulating film on a coplanar flat surface of the first and second conductive strip halves and the second insulating film, said coplanar surface being formed by said polishing.

7. - 9. (Cancelled)

10. (Withdrawn) The method according to claim 6, wherein said first insulating film interposed between successive first and second conductive strip halves is formed by alumina-CVD.

11. (Withdrawn) The method according to claim 10, wherein said first insulating film is formed by an atomic layer process, in which Al(CH₃)₃ or AlCl₃ and H₂O, N₂, N₂O or H₂O₂ are alternately projected intermittently at a temperature of 100-700°C under a reduced pressure state of 1-2 Torr.

12. (Currently Amended) A conductive pattern comprising:

- a substrate having an electrically insulating surface;
- a plurality of first conductive strip halves of a first conductive strip group, said first conductive strip halves having a second width and being arranged on the surface of the substrate such that the first conductive strip halves are separated from each other to form depressions having a first width;
- a plurality of first conductive strip halves of a second conductive strip group, said first conductive strip halves having a fourth width larger than the second width and being arranged on the surface of the substrate such that the first conductive strip halves are separated from each other to form depressions having a third width larger than the first width;
- a first insulating film formed on the surface of the substrate and surfaces of the depressions formed between successive first conductive strip halves of the first and second conductive strip groups;
- a second insulating film formed on a portion of the surface of the substrate at which said first conductive strip halves of the first and second conductive strip groups are not formed;
- a plurality of second conductive strip halves of the first conductive strip group formed on the first insulating layer such that said depressions formed between successive first

conductive strip halves of the first conductive strip group are filled with the second conductive strip halves of the second conductive strip group;

a plurality of second conductive strip halves of the second conductive strip group formed on the first insulating film such that said depressions formed between successive first conductive strip halves of the second conductive strip group are filled with the second conductive strip halves of the second conductive strip group, each of said second conductive strip halves of the second conductive strip group having a two-layer structure having a first conductive CVD film formed by CVD and a second conductive electrolytic plating film formed by electrolytic plating; and

a third insulating film formed on a coplanar flat surface of the first and second conductive strip halves of the first conductive strip group, the first and second conductive strip halves of the second conductive strip group and the second insulting film.

13. (Currently Amended) The conductive pattern according to claim 12, wherein each of said first conductive strip halves of the first and second conductive strip groups include includes a conductive electrolytic plating strips formed by electrolytic plating film.

14. (Currently Amended) The conductive pattern according to claim 13, wherein the conductive electrolytic plating strip of each of said first conductive strip halves of the first and second conductive strip groups include includes a conductive Cu-plating film strips formed by electrolytic plating of copper, each of said second conductive strip halves of the first conductive strip group includes a Cu-CVD film, each of said first conductive film-CVD-films of the second conductive strip halves of the first and second conductive strip groups is formed by group includes a Cu-CVD film and each of said second conductive film electrolytic plating films of the second conductive strip halves of the first and second conductive strip groups is formed by Cu-CVD group includes a Cu-plating film.

15. (Currently Amended) The conductive pattern according to claim 12, wherein said first insulating film interposed between said first and second conductive strip halves of the first and second conductive strip groups ~~is formed by includes~~ an alumina-CVD film.

16. (Currently Amended and Withdrawn) A method of manufacturing the conductive pattern as claimed in claim 12, comprising ~~the steps of:~~

forming, on an electrically insulating surface of a substrate, ~~a~~the plurality of first conductive strip halves of a first conductive strip group having a second width and being arranged such that said first conductive strip halves of the first conductive strip group are separated from each other to form depressions having a first width, and ~~a~~the plurality of first conductive strip halves of a second conductive strip group having a fourth width larger than the second width and being arranged such that the first conductive strip halves of the second conductive strip group are separated from each other to form depressions having a third width larger than the first width;

forming a first insulating film on the surface of the substrate and surfaces of the first conductive strip halves of the first and second conductive strip groups;

forming a covering film selectively on a region in which said first and second conductive strip groups are formed;

forming a second insulating film on a region in which the first and second conductive strip groups are not formed;

forming, after removing said covering film, a first conductive film by CVD on said first insulating film such that the depressions formed between said first conductive strip halves of the first conductive strip group are completely filled with the first conductive film and the depressions formed between said first conductive strip halves of the second conductive strip group are partially filled with the first conductive film;

forming a second conductive film by electrolytic plating on the first conductive film such that the depressions formed between successive first conductive strip halves of the second conductive strip group are completely filled; polishing said first and second conductive films, a portion of said first insulating film covering the surfaces of the first conductive strip halves of the first and second conductive strip groups and said second insulating film such that surfaces of the first conductive strip halves of the first and second conductive strip groups are exposed to form a the plurality of second conductive strip halves of the second conductive strip group arranged in said depressions formed between successive first conductive strip halves of the first conductive strip group and made by said first conductive film and to form athe plurality of second conductive strip halves of the second conductive strip group arranged in said depressions formed between successive first conductive strip halves of the second conductive strip group and having a two-layer structure composed of the first conductive film formed by CVD and the second conductive film formed by electrolytic plating; and

forming a third insulating film on a coplanar flat surface of the first and second conductive strip halves of the first and second conductive strip groups and the second insulating film.

17. - 18. (Cancelled)

19. (Withdrawn) The method according to claim 16, wherein said first insulating film interposed between successive conductive strips of the first and second conductive strip halves of the first and second conductive strip groups is formed by alumina-CVD.

20. (Withdrawn) The method according to claim 19, wherein said first insulating film is formed by an atomic layer process, in which Al(CH₃)₃ or AlCl₃ and H₂O, N₂, N₂O or H₂O₂ are alternately projected intermittently at a temperature of 100-700°C under a reduced pressure state of 1-2 Torr.

21. - 53. (Cancelled)

54. (New) A conductive pattern comprising:

a substrate having an electrically insulating surface;

a plurality of first conductive strips arranged on the surface of the substrate such that the first conductive strips are separated from each other to form depressions, each of said first conductive strips including an electrolytic plating strip;

a first insulating film formed on the surface of the substrate and surfaces of the depressions;

a second insulating film formed on a portion of the surface of the substrate at which said first conductive strips are not formed;

a plurality of second conductive strips formed on the first insulating film such that said depressions formed between successive first conductive strip halves are filled with the second conductive strips, each of said second conductive strips include a conductive CVD-strip; and

a third insulating film formed on a coplanar flat surface of the first and second conductive strips and second insulating film.

55. (New) The conductive pattern according to claim 54, wherein each of said first conductive strips includes a conductive electrolytic plating film.

56. (New) The conductive pattern according to claim 55, wherein each of said first conductive strips includes a Cu-plating film and each of said second conductive strips includes a Cu-CVD film.

57. (New) The conductive pattern according to claim 54, wherein said first insulating film interposed between said first and second conductive strips includes an alumina-CVD film.